



P1092623-7

**IN THE UNITED STATES PATENT OFFICE**

Inventors: F. Kish, et al. Serial No.: Unassigned  
 Filed: Herewith Examiner Unassigned  
 Art Unit: 2503  
 For: Wafer Bonding of Light Emitting Diode Layers

**PRELIMINARY AMENDMENT**

Honorable Assistant Commissioner of  
 Patents  
 Washington, D.C. 20231

Dear Sir:

Please enter the following amendments in this case before considering its patentability.

**In The Claims:**

Please amend claim 14 as indicated below.

14 (Twice Amended). A light emitting semiconductor device comprising:

an arrangement of semiconductor layers for generating light in response to a conduction of current;

D2 an optically transparent wafer-bond layer coupled to said semiconductor layers, an interface of said wafer-bond layer with the semiconductor layers exhibiting properties characteristic of layers that have undergone wafer bonding, including a conductive ohmic bond to said semiconductor layers and being mechanically robust ; and

electrode means for applying a current to said arrangement of semiconductor layers.

Cancel claim 18, without prejudice.

Please enter new claims 38 through 46: